

# APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

<b>Title of Invention</b>	Method for Manufacturing Buried Insulating Layer Type Single Crystal Silicon Carbide Substrate and Manufacturing Device for the Same
Application Type :	regular, utility
Attorney Docket Number :	040091
Correspondence address:	
Customer Number:	23850
	
Priority Data:	
Doc.No: 2003-84056; Country -JP ; Date: 2003-03-26 us-priority-claimed	
Inventors Information:	
<u>Inventor 1:</u>	
<b>Applicant Authority Type:</b>	Inventor
<b>Citizenship:</b>	JP
<b>Given Name:</b>	Katsutoshi
<b>Family Name:</b>	IZUMI
<b>Residence:</b>	
<b>City of Residence:</b>	Osaka
<b>Country of Residence:</b>	JP
<b>Address-1 of Mailing Address:</b>	c/o Osaka Prefecture University, 1-1, Gakuen-cho,
<b>Address-2 of Mailing Address:</b>	Sakai,
<b>City of Mailing Address:</b>	Osaka
<b>State of Mailing Address:</b>	
<b>Postal Code of Mailing Address:</b>	599-8531
<b>Country of Mailing Address:</b>	JP
<b>Phone:</b>	
<b>Fax:</b>	
<b>E-mail:</b>	
<u>Inventor 2:</u>	
<b>Applicant Authority Type:</b>	Inventor
<b>Citizenship:</b>	JP

<b>Given Name:</b>	Motoi
<b>Family Name:</b>	NAKAO
<b>Residence:</b>	
<b>City of Residence:</b>	Osaka
<b>Country of Residence:</b>	JP
<b>Address-1 of Mailing Address:</b>	c/o Osaka Prefecture University, 1-1, Gakuen-cho,
<b>Address-2 of Mailing Address:</b>	Sakai,
<b>City of Mailing Address:</b>	Osaka
<b>State of Mailing Address:</b>	
<b>Postal Code of Mailing Address:</b>	599-8531
<b>Country of Mailing Address:</b>	JP
<b>Phone:</b>	
<b>Fax:</b>	
<b>E-mail:</b>	

Inventor 3:

<b>Applicant Authority Type:</b>	Inventor
<b>Citizenship:</b>	JP
<b>Given Name:</b>	Yoshiaki
<b>Family Name:</b>	OHBAYASHI
<b>Residence:</b>	
<b>City of Residence:</b>	Nara
<b>Country of Residence:</b>	JP
<b>Address-1 of Mailing Address:</b>	c/o Hosiden Corporation, 4-33, Kitakyuhoji
<b>Address-2 of Mailing Address:</b>	1-chome, Yao-shi,
<b>City of Mailing Address:</b>	Osaka
<b>State of Mailing Address:</b>	
<b>Postal Code of Mailing Address:</b>	581-0071
<b>Country of Mailing Address:</b>	JP
<b>Phone:</b>	
<b>Fax:</b>	
<b>E-mail:</b>	

Inventor 4:

<b>Applicant Authority Type:</b>	Inventor
<b>Citizenship:</b>	JP
<b>Given Name:</b>	Keiji
<b>Family Name:</b>	MINE
<b>Residence:</b>	
<b>City of Residence:</b>	Osaka
<b>Country of Residence:</b>	JP
<b>Address-1 of Mailing Address:</b>	c/o Hosiden Corporation, 4-33, Kitakyuhoji

<b>Address-2 of Mailing Address:</b>	1-chome, Yao-shi,
<b>City of Mailing Address:</b>	Osaka
<b>State of Mailing Address:</b>	
<b>Postal Code of Mailing Address:</b>	581-0071
<b>Country of Mailing Address:</b>	JP
<b>Phone:</b>	
<b>Fax:</b>	
<b>E-mail:</b>	

Inventor 5:

<b>Applicant Authority Type:</b>	Inventor
<b>Citizenship:</b>	JP
<b>Given Name:</b>	Seisaku
<b>Family Name:</b>	HIRAI
<b>Residence:</b>	
<b>City of Residence:</b>	Osaka
<b>Country of Residence:</b>	JP
<b>Address-1 of Mailing Address:</b>	c/o Hosiden Corporation, 4-33, Kitakyuhoji
<b>Address-2 of Mailing Address:</b>	1-chome, Yao-shi,
<b>City of Mailing Address:</b>	Osaka
<b>State of Mailing Address:</b>	
<b>Postal Code of Mailing Address:</b>	581-0071
<b>Country of Mailing Address:</b>	JP
<b>Phone:</b>	
<b>Fax:</b>	
<b>E-mail:</b>	

Inventor 6:

<b>Applicant Authority Type:</b>	Inventor
<b>Citizenship:</b>	JP
<b>Given Name:</b>	Fumihiko
<b>Family Name:</b>	JOBE
<b>Residence:</b>	
<b>City of Residence:</b>	Osaka
<b>Country of Residence:</b>	JP
<b>Address-1 of Mailing Address:</b>	c/o Hosiden Corporation, 4-33, Kitakyuhoji
<b>Address-2 of Mailing Address:</b>	1-chome, Yao-shi,
<b>City of Mailing Address:</b>	Osaka
<b>State of Mailing Address:</b>	
<b>Postal Code of Mailing Address:</b>	581-0071
<b>Country of Mailing Address:</b>	JP
<b>Phone:</b>	

**Fax:**

**E-mail:**

Inventor 7:

**Applicant Authority Type:** Inventor  
**Citizenship:** JP  
**Given Name:** Tomoyuki  
**Family Name:** TANAKA  
**Residence:**  
**City of Residence:** Osaka  
**Country of Residence:** JP  
**Address-1 of Mailing Address:** c/o Hosiden Corporation, 4-33, Kitakyuhoji  
**Address-2 of Mailing Address:** 1-chome, Yao-shi,  
**City of Mailing Address:** Osaka  
**State of Mailing Address:**  
**Postal Code of Mailing Address:** 581-0071  
**Country of Mailing Address:** JP  
**Phone:**  
**Fax:**  
**E-mail:**

**Attorney Information:**

practitioner(s) at Customer Number:

23850



as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

Assignee 1:

**Organization Name:** Osaka Prefecture,  
**Address-1 of Mailing Address:** 2-1-22, Otemae,  
**Address-2 of Mailing Address:** Chuo-ku, Osaka-shi,  
**City of Mailing Address:** Osaka,  
**State of Mailing Address:**  
**Postal Code of Mailing Address:** 540-8570  
**Country of Mailing Address:** JP

**Phone:**

**Fax:**

**E-mail:**

Assignee 2:

**Organization Name:** Hosiden Corporation  
**Address-1 of Mailing Address:** 4-33, Kitakyuhoji 1-chome,

<b>Address-2 of Mailing Address:</b>	Yao-shi,
<b>City of Mailing Address:</b>	Osaka,
<b>State of Mailing Address:</b>	
<b>Postal Code of Mailing Address:</b>	581-0071
<b>Country of Mailing Address:</b>	JP
<b>Phone:</b>	
<b>Fax:</b>	
<b>E-mail:</b>	